

e-Manufacturing & Design Collaboration 2014

Invited Speech:

EFEM total solution for next generation process



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About the Speaker

Young Y.H. Hung received his Bachelor degree in physics department from Chung-Yuan Christian University in 1993. He joined Semiconductor equipment supplier for yield improvement and applications engineering since year 1996. He is currently working at Hirata Corporation, serving as Manager of Sales and Engineering Department. He is based in the Taoyuan, Taiwan office.

Abstract

Wafer handling process directly impact product yield due to particles, vibrations, cracks, and so on. To go with new IC process, wafers became thinner and more difficult to handle. The same as next generation process, chemical filter and particles induced by wafer handling became more critical than past. To overcome such situation, Hirata, the automation and handling expertise develop new technologies and co-work with our customers to provide solutions for future IC process tool system.